DDR 24-Bit to 48-Bit Registered Buffer

Features

- Differential clock signals.
- Supports SSTL_2 class II specifications on inputs and outputs.
- Low voltage operation.
 - $V_{DD} = 2.3V$ to 2.7V.
- Available in 114 ball BGA package.
 Industrial temperature range also available.

Product Description

The 24-Bit to 48-Bit ASM4SSTVF32852 is a universal bus driver designed for 2.3V to 2.7V V_{DD} operation and SSTL_2 I/O levels except for the LVCMOS RESETB input.

Data flow from D to Q is controlled by the differential clock (CLK/CLKB) and a control signal (RESETB). The positive edge of CLK is used to trigger the data flow, and CLKB is used to maintain sufficient noise margins, whereas the RESETB, an LVCMOS asynchronous signal is intended for use at the time of power-up only.

The ASM4SSTVF32852 supports a low power standby mode of operation. A logic "Low" level at RESETB, assures that all internal registers and outputs (Q) are reset to a logic "Low" state, and that all input receivers, data (D) buffers, and clock (CLK/CLKB) are switched off. Please note that RESETB must always be supported with a LVCMOS levels at a valid logic state since VREF may not be stable during power-up.

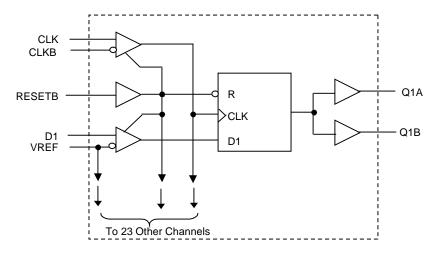
To ensure that outputs are at a defined logic state before a stable clock has been supplied, RESETB must be held at a logic "Low" level during power-up.

In the DDR DIMM application, RESETB is specified to be asynchronous with respect to CLK/CLKB. Therefore, no timing relationship can be guaranteed between the two signals. When entering a low-power standby state, the register will be cleared and the outputs will be driven to a logic "Low" level quickly relative to the time to disable the differential input receivers. This ensures there are no "glitches" on any output. However, when coming out of low power standby state, the register will become active quickly relative to the time taken to enable the differential input receivers. When the data inputs are at a logic level "Low" and the clock is stable during the "Low-to-High" transition of RESETB until the input receivers are fully enabled, the design ensures that the outputs will remain at a logic "Low" level.

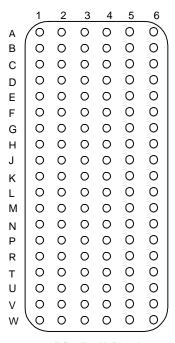
Applications

- DDR Memory Modules.
- Provides complete DDR DIMM logic solution with ASM5CVF857, ASM4SSTVF16857 and ASM4SSTVF16859.
- SSTL_2 compatible data registers.

Block Diagram



Pin Configurations



114-Pin Ball BGA

Pin Description

Pin #	Pin Name	Туре	Description
R1, P1, N1, N2, M1, L2, L1, K1, K2, J2, J1, H1, G1, G2, F1, F2, E1, D1, D2, C1, C2, B1, A1, A2	Q (24:1)A	0	Data output.
R6, P6, N6,N5,M6, L5, L6, K6, K5, J5, J6, H6, G6, G5, F6, F5, E6, D6, D5, C6, C5, B6, A6, A5	Q (24:1)B	0	Data output.
E2, B3, D3, G3, J3, L3, M3, P3, B4, D4, G4, J4, L4, M4, P4, E5	GND	Р	Ground.
B2, M2, P2, C3, E3, F3, H3, K3, N3, C4, E4, F4, H4, K4, N4, B5, M5, P5	VDDQ	Р	Output supply voltage, 2,5V nominal.
W4, V4, U4, W5, W6, V5, T4, V6, U6, U5, T6, T5, W3, V3, U3, W2, W1, V2, T3, V1, U1, U2, T1, T2	D(24:1)	ı	Data input.
А3	CLK	I	Positive master clock input.
A4	CLKB	I	Negative master clock input.
H2, H5, R2, R5	VDD	Р	Core supply voltage, 2.5V nominal.
R3	RESETB	I	Reset (Active Low).
R4	VREF	I	Input reference, 1.25V nominal.

rev 2.0

Pin Configuration Assignments

	1	2	3	4	5	6
А	Q2A	Q1A	CLK	CLKB	Q1B	Q2B
В	Q3A	VDDQ	GND	GND	VDDQ	Q3B
С	Q5A	Q4A	VDDQ	VDDQ	Q4B	Q5B
D	Q7A	Q6A	GND	GND	Q6B	Q7B
E	Q8A	GND	VDDQ	VDDQ	GND	Q8B
F	Q10A	Q9A	VDDQ	VDDQ	Q9B	Q10B
G	Q12A	Q11A	GND	GND	Q11B	Q12B
Н	Q13A	VDD	VDDQ	VDDQ	VDD	Q13B
J	Q14A	Q15A	GND	GND	Q15B	Q14B
К	Q17A	Q16A	VDDQ	VDDQ	Q16B	Q17B
L	Q18A	Q19A	GND	GND	Q19B	Q18B
М	Q20A	VDDQ	GND	GND	VDDQ	Q20B
N	Q22A	Q21A	VDDQ	VDDQ	Q21B	Q22B
Р	Q23A	VDDQ	GND	GND	VDDQ	Q23B
R	Q24A	VDD	RESETB	VREF	VDD	Q24B
Т	D2	D1	D6	D18	D13	D14
U	D4	D3	D10	D22	D15	D16
V	D5	D7	D11	D23	D19	D17
W	D8	D9	D12	D24	D21	D20

Truth Table¹

	Q Outputs			
RESET#	CLK	CLK#	D	Q
L	X or floating	X or floating	X or floating	L
Н	1	\	Н	Н
Н	1	<u> </u>	L	L
Н	L or H	L or H	Х	Q ₀ ²

Note: 1. H=High signal level, L=Low signal level, ↑= transition from low to high, ↓= transition from high to low, X = don't care 2. Output level before the indicated steady state input conditions were established.

Absolute Maximum Ratings

Parameter	Min	Max	Unit
Storage Temperature	-65	+150	°C
Supply Voltage	-0.5	3.6	V
Input Voltage ¹	-0.5	V _{DD} + 0.5	V
Output Voltage ^{1,2}	-0.5	V _{DD} + 0.5	V
Input Clamp Current	±	50	mA
Output Clamp Current	±:	mA	
Continuous Output Current	±:	mA	
VDD, VDDQ or GND current/pin	10	mA	
Package Thermal Impedance ³	5	5	°C/W

Note

- 1. The input and output negative voltage ratings may be excluded if the input and output clamp ratings are observed.
- 2. This current will flow only when the output is in the high state level $V_0 > V_{\text{DDQ}}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for prolonged periods can affect device reliability.

Recommended Operating Conditions

Guaranteed by design. Not 100% tested in production.

Parameter	Description		Min	Тур	Max	Unit
V_{DD}	Supply voltage		2.3	2.5	2.7	V
V_{DDQ}	Output supply voltage		2.3	2.5	2.7	V
V_{REF}	Reference voltage		1.15	1.25	1.35	V
V_{TT}	Termination voltage		V _{REF} - 0.04	V_{REF}	V _{REF} + 0.04	V
Vı	Input voltage		0		V_{DDQ}	V
$V_{\text{IH(DC)}}$	DC input high voltage		V _{REF} + 0.15			V
V _{IH(AC)}	AC input high voltage	Data	V _{REF} + 0.31			V
$V_{\text{IL}(DC)}$	DC input low voltage	Inputs			V _{REF} - 0.15	V
$V_{\text{IL(AC)}}$	AC input low voltage				V _{REF} - 0.31	V
V _{IH}	Input high voltage level	RESETB	1.7			V
V_{IL}	Input low voltage level	KLOLIB			0.7	V
V _{ICR}	Common mode input range	CLK	0.97		1.53	V
V_{ID}	Differential input voltage	CLKB	0.36			V
V_{IX}	Cross-point voltage of differential clock pair		(V _{DDQ} /2) - 0.2		(V _{DDQ} /2) +0.2	V
I _{OH}	High-level output current				-19	mA
I _{OI}	Low-level output current				19	mA
T _A	Operating free-air temperature		0		70	°C

DC Electrical Characteristics

 T_{A} = 0°C to 70°C, V_{DD} = 2.5 \pm 0.2V, and V_{DDQ} = 2.5 \pm 0.2V (unless otherwise stated)

Guaranteed by design. Not 100% production tested.

Symbol	Parameter	Test conditions		V _{DDQ}	Min	Тур	Max	Units
V _{IK}		I ₁ = -18 mA		2.3 V			-1.2	V
V _{OH}		I _{OH} = -100 μA		2.3 V to 2.7 V	V _{DD} - 0.2			٧
VOH		I _{OH} = -16 mA		2.3 V	2.05			V
V_{OL}		I _{OL} = 100 μA		2.3 V to 2.7 V			0.2	V
V OL		I _{OL} = 16 mA		2.3 V			0.20	٧
I _I	All inputs	$V_{I} = V_{DD}$ or GND		2.7 V			± 5	μΑ
I _{DD}	Standby (static)	RESETB = GND					0.01	μΑ
סטי	Operating (static)	$V_{I} = V_{IH(AC)}$ or $V_{IL(AC)}$, RESETB = V_{DD}	l ₀ = 0			40		mA
	Dynamic operating (clock only)	RESETB = V_{DD} , $V_{I} = V_{IH(AC)}$ or $V_{IL(AC)}$, CLK and CLKB switching 50% duty cycle		2.5V		35		μΑ/clock MHz
I _{DDD}	Dynamic operating (per each data input)	RESETB = V _{DD} , V _I = V _{IH(AC)} or V _{IL(AC)} , CLK and CLKB = switching 50% duty cycle; One data input switching at half clock frequency, 50% duty cycle					7	
r _{OH}	Output high	I _{OH} = -20 mA		2.3 V to 2.7 V		12		Ω
r _{OL}	Output low	I _{OL} = 20 mA		2.3 V to 2.7 V		10		Ω
r _{O(D)}	r _{OH} - r _{OL} each separate bit	I _O = 20 mA, T _A = 25° C		2.5 V			4	Ω
C _i	Data inputs	$V_{I} = V_{REF} \pm 350 \text{ mV}, \ V_{ICR} = 1.25 \text{ V}$	<i>'</i> ,	2.5 V	2.5		3.5	pF
O _i	CLK & CLKB	$V_{I(PP)} = 360 \text{ mV}$		2.5 V	2.5		3.5	pF

rev 2.0 **Timing Requirements**

(Over recommended operating free-air temperature range, unless otherwise noted).

Symbol	Parameters			V _{DD} = 2.5V±0.2V		
		Min	Max	Unit		
f _{CLOCK}	Clock frequency			200	MHz	
T_PD	Clock to output time			2.7	ns	
T _{RST}	Reset to output time			4.5	ns	
ts	Setup time, fast slew rate ^{2,4}	Data before CLK↑, CLKB↓	0.5		ns	
15	Setup time, slow slew rate 3,4	Data before CERT, CERD	0.7		ns	
t _h	Hold time, fast slew rate ^{2,4}	Data after CLK↑, CLKB↓	0.3		ns	
rn 	Hold time, slow slew rate 3,4	Bata and GERT, GERBY	0.5		ns	
t _{SL}	Output slew rate			4	V/ns	

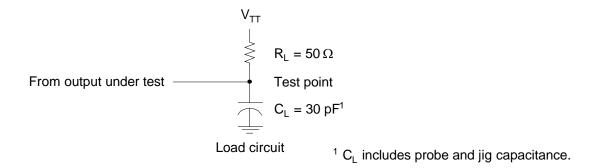
- Note: 1. Guaranteed by design, not 100% tested in production.
- 2. For data signal input slew rate >= 1V/ns
- 3. For data signal input slew rate >= 0.5 V/ns and < 1V/ns
- 4. CLK,CLKB signals input slew rates are >=1V/ns

Switching Characteristics

(Over recommended operating free-air temperature range unless otherwise noted.)

Symbol	From (input)	To (output)	V _{DD}	Units		
			Min	Тур	Max	
f _{max}			200	1	_	MHz
t _{PD}	CLK, CLKB	Q	1.9		2.7	ns
t _{phl}	RESETB	Q	_	_	4.5	ns

Parameter Measurement Information (V_{DD} = 2.5 V ± 0.2V)

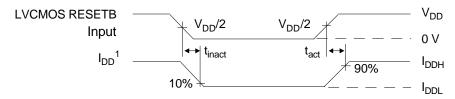


Voltage and Current Waveforms

In the following waveforms, note that all input pulses are supplied by generators having the following characteristics:

- PRR \leq 10 MHz, $Z_0 = 50 \Omega$, input slew rate = 1 V/ns \pm 20% (unless otherwise specified).
- The outputs are measured one at a time with one transition per measurement.
- $V_{TT} = V_{REF} = V_{DDQ}/2$.
- $V_{IH} = V_{REF} + 310 \text{ mV}$ (AC voltage levels) for differential inputs. $V_{IH} = V_{DD}$ for LVCMOS input.
- V_{IL} = V_{REF} 310 mV (AC voltage levels) for differential inputs. V_{IL} = GND for LVCMOS input.
- t_{PLH} and t_{PHL} are the same as t_{pd}.

Input active and inactive times

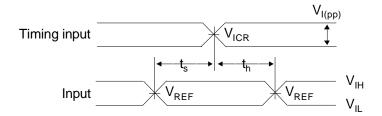


 $^{^{1}}$ I_{DD} tested with clock and data inputs held at V _{DD} or GND, and I $_{\rm O}$ = 0 mA.

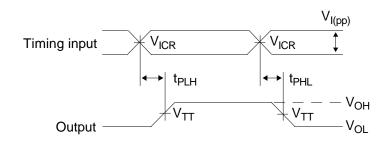
Pulse duration

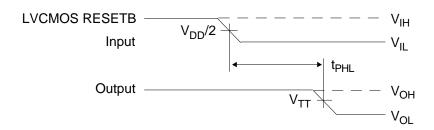


Setup and hold times



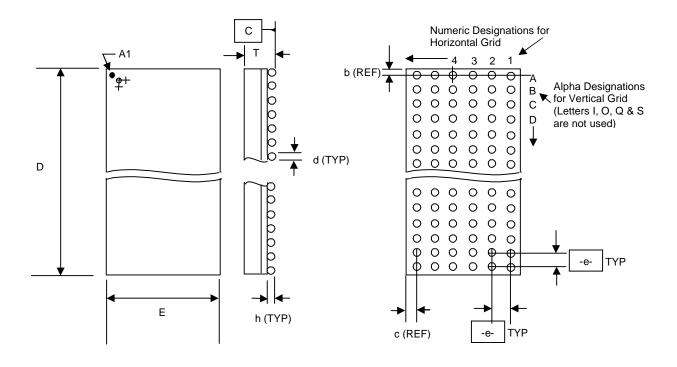
rev 2.0 Propagation delay times





Package Dimensions

114-Pin Ball BGA



_	_	T Min/Max		E	BALL GRI	D	a	h Min/Max	REF. DIMENSION	
D	_ E	I WIII/Wax	е	HORIZ	VERT	TOTAL	a	n wiin/wax	b	С
16.00	5.50	1.30/1.50	0.80	6	19	114	0.46	0.31/0.41	0.80	0.75
BSC	BSC		BSC	•						

Ordering Codes

Ordering Number	Ordering Number Marking Packag		Quantity per reel	Temperature
ASM4SSTVF32852-114BT	AS4SSTVF32852B	114-pin Ball, BGA, tray/tube		0°C to 70°C
ASM4SSTVF32852-114BR	AS4SSTVF32852B	114-pin Ball, BGA, tape and reel	2500	0°C to 70°C
ASM4ISSTVF32852-114BT	AS4ISSTVF32852B	114-pin Ball, BGA, tray/tube		-40°C to +85°C
ASM4ISSTVF32852-114BR	AS4ISSTVF32852B	114-pin Ball, BGA, tape and reel	2500	-40°C to +85°C



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